

Product Change Notice PCN98007

A change in the mold compound and die attach epoxy used to fabricate Xilinx PLCC and QFP packages

Subject: A change in the mold compound and die attach epoxy used to fabricate Xilinx PLCC and QFP packages (excluding VQFP and TQFP packages)

Products Affected: All Xilinx PLCC and QFP packages assembled at AMKOR and SPIL.

Change Description: The mold compound and die attach epoxy used to fabricate Xilinx plastic packaged products at AMKOR (including Korea and Philippines) and SPIL (Taiwan) assembly sites are being changed. Currently PLCC packages are fabricated with Sumitomo 6300H while QFP packages are fabricated with Sumitomo 7304LC. In both cases, the current die attach epoxy is Ablestik 84-1LMIS. After the date indicated below (date code 9845), PLCC and QFP packages will all be molded with Nitto MP8000 mold compound, and die attach will be done with Ablestik 8361J. [Qualification data](#) is attached.

Reason for Change: Xilinx is transitioning to more modern mold compound and die attach epoxy to improve the package integrity and reliability of our products. Once the transition is complete, Xilinx will announce significant improvements in moisture resistance and shelf life (as measured by J-STD 20).

Key Dates: Product molded after assembly date code 9845 (product molded after 15 November 1998) will use the new materials.

Traceability: Traceability is by date code (see above)

Immediate response to this notification is not required. For any questions regarding this PCN you may contact Xilinx at "pcn@xilinx.com", or by FAX at 408 559 1368.